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Abstract

Semiconductor package with heat spreader

5 A semiconductor package (1) comprises a device carrier (2) having a plurality of contact areas (7) and a semiconductor die (3) having a plurality of die pads (10) of an active surface, the semiconductor die (3) being mounted on the device carrier (2). Connection means (4) to electrically connect the
10 die pads (10) to the contact areas (7) and a heat spreading means (5) mounted on the active surface of the die (3) are provided. The heat spreading means includes an upper plate (11) and a foot ring (12) which protrudes from a bottom surface of the upper plate (11) and which is positioned between
15 the die pads (10) on the active surface such that a cavity (14) is formed between the heat spreading means (5) and the active surface. The cavity is filled with an adhering means (15) interconnecting the heat spreading means (5) and the active surface.

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[Fig. 1]